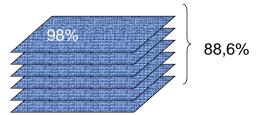
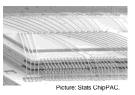




#### **YIELD LOSS \*\*X: 3D INTEGRATION**



Main driver: stacked memories in I package.



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# MANUFACTURING TEST: GOALS & CHALLENGES

Test = Method of guaranteeing product quality
Not all parts are good

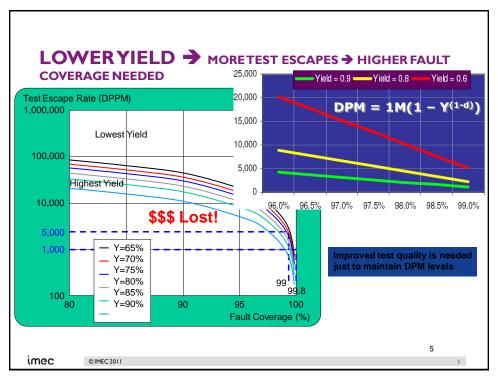
Manufacturing Test = Finding the bad ones

- ► Never let bad parts escape : assure the wanted quality level
- Never throw away good parts : as high as possible yield
  - Over-testing: overly aggressive test falsely identifies good parts as bad
- ► Test as quickly/cheaply as possible

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# THE COST OF TESTING

## Extra Cost for testing

- Additional pins for test
- Additional logic (if core limited) for test
- Additional design time & tools
  - Scan/BIST insertion & functionality check
  - Time for ATPG & manual TPG
  - Simulation time of the vectors
  - ...

Test HW (test board) + SW (10's of k €)

Tester time ≈ 0.035€/second

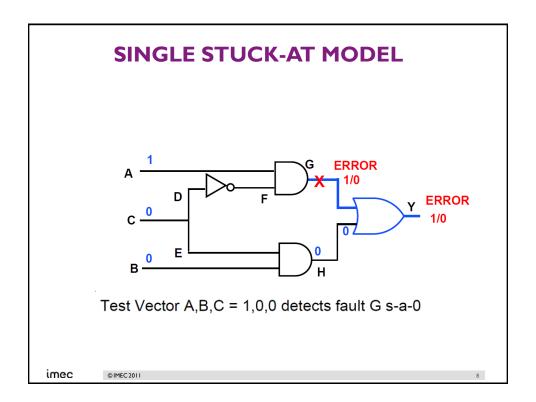
Pattern size supported by Test (ATE) machine

Load of extra patterns = costly!!!!

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# **DSM DEFECTS VS. TESTS Defect Fault Model based Test** Resistive Via's Transition delay Process impurities Bridging IDDQ based) Stuck-at -Metal slivers -Shorts Transition delay Voids in copper Transition delay Systematic Path delay Parameter failure imec © IMEC 2011



Normal

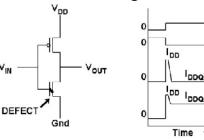
Defect





Measuring the steady state current of the device against a predefined pass/fail threshold (same for all devices)

Classical CMOS "no leakage" → defect



Typ in past 1..10 tests

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# **IDDQ DESIGN-FOR-TEST RULES**

→ tmax ug.pdf

Eg.

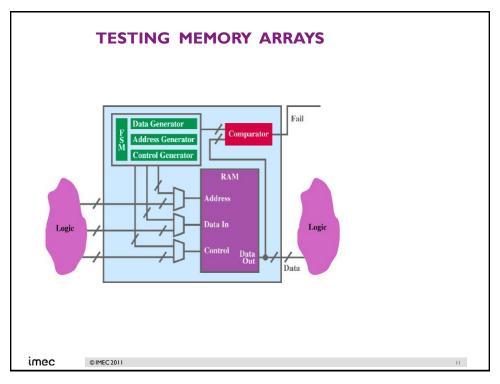
- seperate power rails for IO and core
- disable PU/PD during IDDQ test
- make sure RAM outputs are not Z during IDDQ test

- ...

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# BASIC ATPG FLOW (LOW SPEED PAT) Insertion of test logic and scan chains during rtl design & synthesis Generation of the pre-layout patterns (stuck-at/iddq) Verification(simulation) of pattern subset using dummy sdf Layout (=> change of netlist) Generation of the post-layout patterns (stuck-at/iddq) Verification(simulation) of patterns (subset) using bc & wc sdf



### INSERTION OF TEST LOGIC

- To control analog outputs connected to digital
- To have direct access to asynchronous resets in test mode
- To bypass units in test mode (eg. RAMs)
- To use functional outputs as scan outputs in test mode
- To modify clock structure in test mode

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# **ATPG DESIGN GUIDELINES**

→ tmax ug.pdf

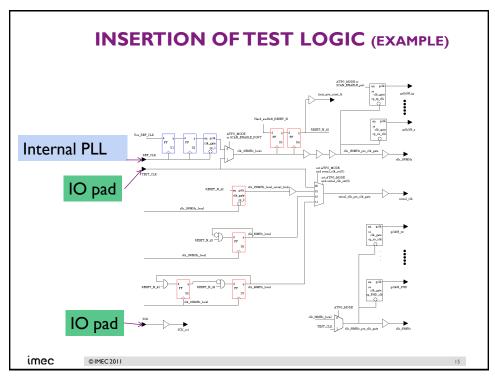
# Eg:

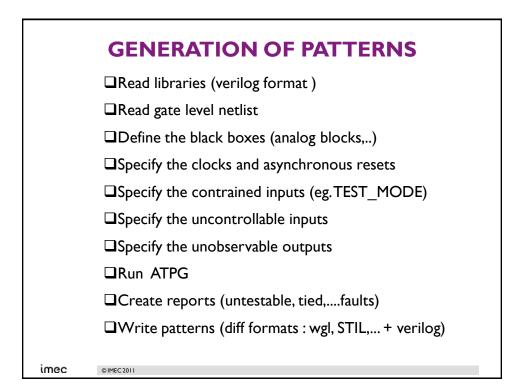
- no clock dividers in ATPG test mode
- no gated clocks in ATPG test mode
- bypass PLLs
- bypass POR
- do not allow path from pulsed input(clock or reset) to both clk and data input of flops in ATPG test mode

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# VERIFICATION(SIMULATION) OF PATTERNS (SUBSET)

- Simulator
- Read netlist
- Read timing (dummy or real sdf)
- Read patterns (mostly in verilog format)
  - Contain expected outputs
- Simulate the patterns
  - Very time consuming
    - I pattern = (#flops in chain) \* clock period + capture cycle
    - + many events!!

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# **PATTERN SETS**

- Simple ATPG patterns (Stuck-at)
- ATPG patterns for IDDQ
- Functional patterns
- At speed functional tests
- ESA projects
- Specific customers
- Normally not done for prototypes

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